

4

3

2

1

REVISIONS

ZONE	REV	DESCRIPTION	DATE	APPROVED

SIZE	QTY	SYM	PLATED	TOL
37	14	+	YES	+/-0.0
36	4	X	YES	+/-0.0
20	34	□	YES	+/-0.0

3320mil

2428mil

NOTES:

1. PRINTED CIRCUIT BOARD IS SHOWN VIEWED FROM COMPONENT SIDE.

2. ALL MATERIALS TO BE ROHS COMPLIANT.

3. FABRICATE PER IPC-6012 AND IPC-6011. INSPECT TO IPC-A-600.

4. BOARD MATERIAL: ROHS COMPLIANT FR-4, LAMINATED SHEET, HTE COPPER CLAD, TYPE GF/GFG, WOVEN GLASS BASE, FLAME RESISTANT, MEETING UL-94V0 OR BETTER. Tg RATING OF 130 DEGREES C OR GREATER. Td RATING OF 340 DEGREES C OR GREATERMATERIAL IN ACCORDANCE WITH IPC-4101.

5. FINISH:

A. PLATED HOLES SHALL HAVE A MINIMUM COPPER THICKNESS OF .0008 IN. AND HAVE A MINIMUM OF 80% COVERAGE.

B. LPI SOLDERMASK PER IPC-SM-840 OVER BARE COPPER (SMOBC). SOLDERMASK REGISTRATION TO BE WITHIN +/- .003 OF IT'S RESPECTIVE CIRCUIT LAYER, NO MASK ON PADS.

C. PLATING TO BE ROHS COMPLIANT, IMMERSION SILVER, PER IPC-4553.

D. HOLE DIMENSIONS APPLY AFTER FINISHING.

E. HOLE TOLERANCE; +/- .003 PLATED AND +/- .005 NON-PLATED. HOLES .018 AND UNDER MAY BE PLUGGED.

6. SILKSCREEN WITH ROHS COMPLIANT WHITE NON-CONDUCTIVE INK, NO INK ON PADS. UL RECOGNIZED VENDOR MARK AND 94V-0 TO APPEAR ON SOLDERSIDE IN ETCH, ROHS COMPLIANT WHITE NON-CONDUCTIVE INK OR LASER MARKING. ROHS COMPLIANT SYMBOL TO APPEAR ON SOLDERSIDE IN ROHS COMPLIANT WHITE NON-CONDUCTIVE INK ONLY.

7. WRAP AND TWIST NOT TO EXCEED .010 IN./IN. FOR COPPER WEIGHT AND BOARD THICKNESS SEE DETAIL 'A'. LAYER TO LAYER REGISTRATION .005 IN.

8. SEE "STACKUP" DETAIL FOR COPPER WEIGHT AND BOARD THICKNESS

9. LAYER TO LAYER REGISTRATION .005 IN.

DETAIL "A"

TOP SILKSCREEN

TOP SOLDERMASK

TOP (COMPONENT) – 1.0 oz

Adjust Thickness

BOTTOM – 1.0 oz

BOTTOM SOLDERMASK

0.062

+/- 10%

STACKUP

FILENAME	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON; 2 PL DECIMALS +/- .005 3 PL DECIMALS +/- .015 ANGLES +/- 1.0 DEGREE	<div><div>ON</div><div>ON Semiconductor</div></div> <div>NCP3020 – 2 Layer 2 Sided FABRICATION DRAWING</div>							
NCP3020_SST.pho;		DRAWN BY	J. Hill	SIZE	FSCM NO	DWG NO	REV		
NCP3020_SMT.pho;									
NCP3020_TOP.pho;		REVISED	02/15/2010			NCP3020_EVB	3		
NCP3020_BOT.pho									
NCP3020_SMB.pho;									
drl001.drl;		SCALE	NA	SHEET	1 OF 1				
drl001.lst									